



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-09-06
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STFU26N60M2	TS4L*MQ6WB62	A	3068	2017-09-06
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	102-16.5-4.5	3	Through-hole	
Comment	TO-220FP ULTRA NARROW LEADS			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.30	Die - Leadframe	219
Lead	11.44	Soft solder	8287

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TS4L*MQ6WB62									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	13.381	mg	supplier	die	Silicon (Si)	7440-21-3		12.850	mg	960317	9312				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.255	mg	19057	185				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.061	mg	4559	44				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.090	mg	6726	65				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.006	mg	448	4				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.088	mg	6576	64				
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.021	mg	2317	22				
				supplier	alloy	Copper (Cu)	7440-50-8		582.709	mg	998306	422253				
				supplier	alloy	Iron (Fe)	7439-89-6		0.268	mg	459	194				
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.490	mg	839	355				
Leadframe	Copper & its alloys	583.698	mg	supplier	metallization	Nickel (Ni)	7440-02-0		0.214	mg	367	155				
				supplier	metallization	Phosphorus (P)	12185-10-3		0.017	mg	29	12				
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	11.436	mg	954990	8287				
				supplier	solder	Silver (Ag)	7440-22-4		0.299	mg	24969	217				
				supplier	solder	Tin (Sn)	7440-31-5		0.240	mg	20041	174				
				Soft solder	Solder	11.975	mg	JIG - R	solder	Aluminium (Al)	7429-90-5		0.920	mg	996750	667
								supplier	wire	Magnesium (Mg)	7439-95-4		0.003	mg	3250	2
								supplier	mold compound	Quartz	14808-60-7		535.479	mg	700000	388028
								supplier	mold compound	Silica, vitreous	60676-86-0		57.373	mg	75000	41575
								supplier	mold compound	Epoxy resin	25068-38-6		107.096	mg	140000	77606
supplier	mold compound	phenol resin	29690-82-2						53.548	mg	70000	38803				
Encapsulation	Other Organic Materials	764.971	mg	supplier	mold compound	metal hydroxide	Proprietary		7.650	mg	10000	5543				
				supplier	mold compound	carbon black	1333-86-4		3.825	mg	5000	2772				
				supplier	solder alloy	Tin (Sn)	7440-31-5		5.052	mg	1000000	3661				
				supplier	solder alloy	Tin (Sn)	7440-31-5		5.052	mg	1000000	3661				
				supplier	solder alloy	Tin (Sn)	7440-31-5		5.052	mg	1000000	3661				
Connections coating	Solder	5.052	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.052	mg	1000000	3661				